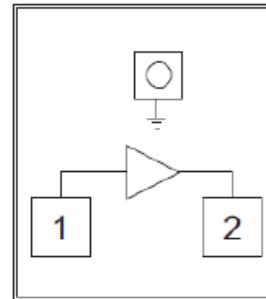


Features

- Operating Frequency: DC-4GHz
- Small Signal Gain: 14.5dB
- Gain Flatness: ± 0.25 dB
- Noise Figure: 4.0dB
- P-1dB: 15.5dBm
- OIP3: 33.5dBm@1GHz with -5dBm input
- Current: 60mA
- 50Ohm input/output
- Die Size: 0.62 x 0.62 x 0.1 mm

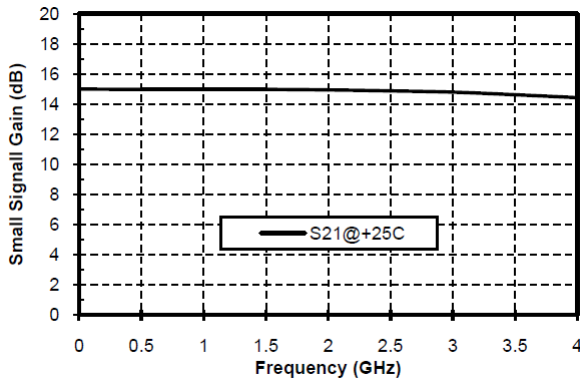
Functional Block Diagram

Typical Applications

- Test Instrumentation
- Microwave Radio & VSAT
- Military & Space
- Telecom Infrastructure
- Fiber Optics

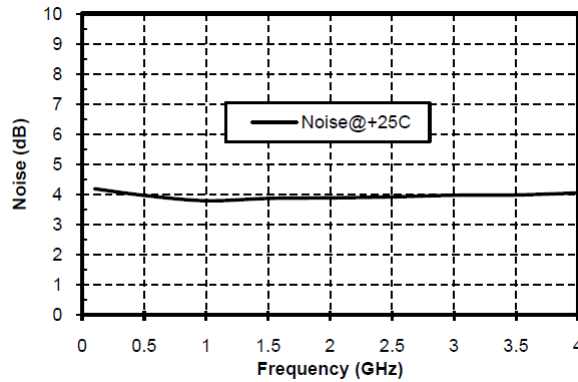
Electrical Specifications
TA = +25°C, VCC=+7V, R_{BIAS}=38.3Ω

Parameters	Min.	Typ.	Max.	Units
Frequency	DC - 4			GHz
Small Signal Gain		14.5		dB
Gain Flatness		± 0.25		dB
Input Return Loss		26		dB
Output Return Loss		22		dB
Reverse Isolation		19		dB
P-1dB	12.5	15.5	17	dBm
Psat	14	16.5	18	dBm
OIP3 @1GHz with -5dBm input		33.5		dBm
Noise Figure		4.0		dB
Static Current		60		mA
Device Voltage, V_{BIAS}	4.4	4.7	5.0	V

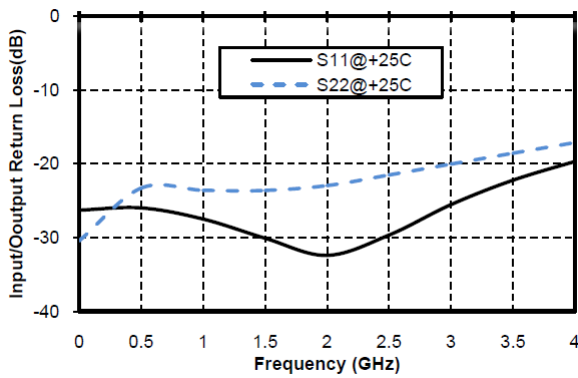
Gain vs. Frequency



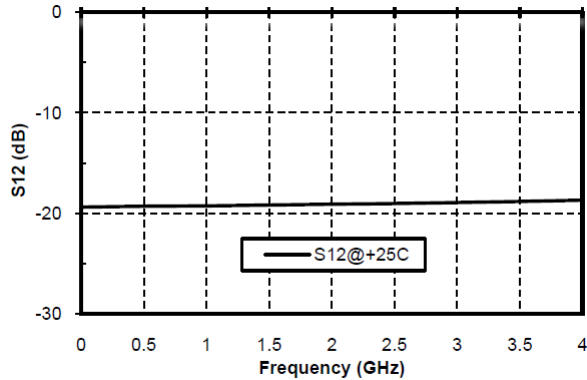
Noise Figure vs. Frequency



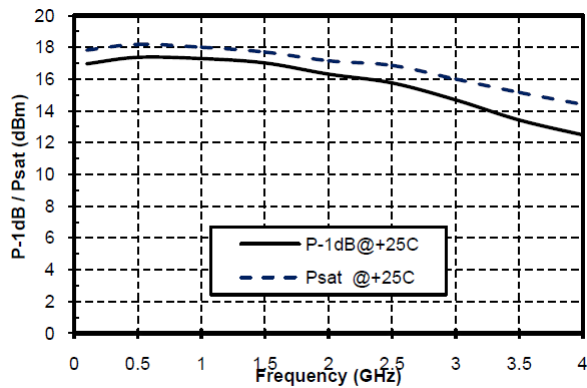
Input/Output Return Loss vs. Frequency



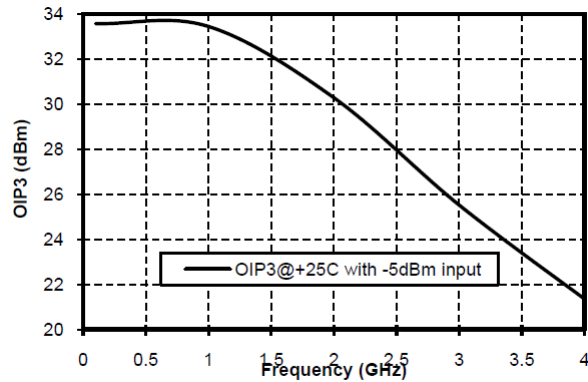
Reverse Isolation vs. Frequency



P-1dB/Psat vs. Frequency

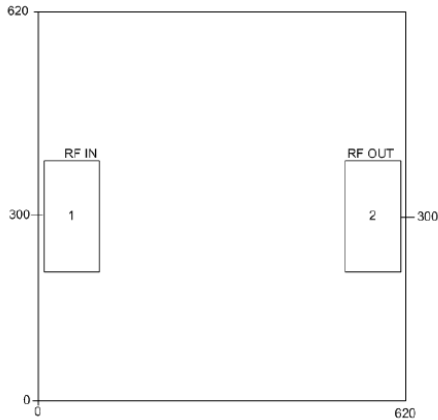


OIP3 with -5dBm input vs. Frequency

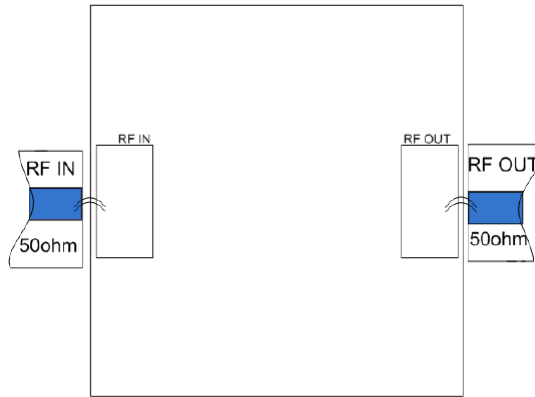


Outline Drawing(Die):

All Dimensions in um



Assembly Drawing(Die):



Pad Description

PAD	Function	Description
1	RF IN	RF input, external DC-blocking capacitor required
2	RF OUT	RF output and DC bias, bias the current by external choke inductor at output terminal , external DC-blocking capacitor required
Die Bottom	GND	Die bottom must be connected to RF/DC ground



Recommended bias circuit

	Device		Frequency (MHz)							
			10	1000	2000					4000
	L1		10μH	270nH	270nH					270nH
	C1, C2		0.01μF	0.01μF	0.01μF					0.01μF
V _{CC} (V)	5	6	7	8	10	12	15	20		
R _{BIAS} (Ω)	7	24	38.3	52.3	80.6	115	158	237		

*Note: R_{BIAS} can be changed with different application condition, $R_{BIAS} = (V_{CC} - V_{BIAS}) / I_{BIAS}$

Notes:

1. Die thickness: 100um
2. Typical bond pad is 100*100 μm²
3. Bond pad metalization: Gold
4. Backside metalization: Gold
5. Backside of the die (GND)
6. No connection required for unlabeled bond pads

Maximum Ratings:

1. RF input power: +25dBm
2. Operating Current: 80mA
3. Storage temperature: -65°C to +150°C
4. Operating temperature: -55°C to +85°C